

OMB No. 0651-0011

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INFORMATION DISCLOSURE STATEMENT 		Atty. Docket No.: 53434USA8C.009		Serial No.:09/690,600			
		Applicant(s):Peter B. Hogerton et al.					
		Filing Date: October 17, 2000		Group: 3729			
U.S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	SubClass	Filing Date If Appropriate
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LT		5,128,746	7/7/92	Pennisi et al.	357	72	
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		Document Number	Date of Publication	Country	Class	SubClass	Translation
							Yes No
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		HEI 1[1989]-164041	6/28/89	Japanese Kokai			x
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Luan Thai			9/2002				RECEIVED MAIL ROOM 2001

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